

Conclusion of Absorption-type Company Split Agreement

Tokyo, December 22, 2009 - Hitachi High-Technologies Corporation and Renesas Technology Corp. today announced that Hitachi High-Tech Instruments Co., Ltd., a wholly owned subsidiary of Hitachi High-Technologies, and Renesas Eastern Japan Semiconductor, Inc., a wholly owned subsidiary of Renesas Technology, today entered into an absorption-type company split agreement regarding the transfer of the semiconductor manufacturing equipment business, which is based at the Yamanashi Factory of Renesas Eastern Japan Semiconductor, to Hitachi High-Tech Instruments. Both companies, as well as Hitachi High-Technologies and Renesas Technology, also today signed a definitive agreement regarding this business transfer. This is an update to the announcement which Hitachi High-Technologies and Renesas Technology made on October 28, 2009 in the press release titled “Hitachi High-Technologies to Acquire Semiconductor Manufacturing Equipment Business from Renesas.” Method of the business transfer, the background and date of transfer, are as follows.

1. Method of business transfer

The transfer method shall be an absorption-type company split with Renesas Eastern Japan Semiconductor as the splitting company and Hitachi High-Tech Instruments as the succeeding company, transferring the semiconductor back-end process manufacturing equipment business of Renesas Eastern Japan Semiconductor to Hitachi High-Tech Instruments.

2. Background

Renesas Eastern Japan Semiconductor is currently charged with the development and manufacture of semiconductor back-end process manufacturing equipment, with Hitachi High-Technologies responsible for global sales of most of these products. However, both Hitachi High-Technologies and Renesas Technology have acknowledged that the integrated management of development through to manufacturing, sales and services pertaining to semiconductor back-end process manufacturing equipment is the most desirable option going forward for responding flexibly to the changing market environment and accelerating the development of new products that reflect customer needs. Furthermore, Hitachi High-Technologies aims to expand business by bringing even more superior products to market through synergies with technological and development capabilities honed by Hitachi High-Tech Instruments in the surface mount

systems and semiconductor manufacturing equipment business over the years, leading to the signing of the definitive agreement with Renesas Technology. With this transfer, Hitachi High-Technologies aims to establish and strengthen its business base in the semiconductor back-end process manufacturing equipment business, where market expansion is widely anticipated. Renesas Technology, for its part, is promoting effective resource utilization to enhance its core competency, the microcontroller business, so that it can realize a more stable and stronger management base.

3. Effective date

The effective date of the absorption-type company split is scheduled to be April 1, 2010.

About Hitachi High-Technologies Corporation

Hitachi High-Technologies Corporation (TSE:8036) is a global company that has engaged in a broad range of fields, including electronic device systems, life sciences, information systems & electronic components and advanced industrial products. Hitachi High-Technologies is a subsidiary of Hitachi Ltd. (TSE:6501, NYSE:HIT) Founded in 1947, the Headquarter is located in Tokyo and there are 25 offices in Japan and 59 offices in twenty-seven countries. The company's consolidated sales are \$7.8 billion in FY2008. For further information, visit <http://www.hitachi-hitec.com/global/>

About Renesas Technology Corp.

Renesas Technology Corp. is the world's No.1 supplier of microcontrollers and one of the world's leading semiconductor system solutions providers for mobile, automotive and PC/AV (Audio Visual) markets. It is also a leading provider of Power MOSFETs, Smart Card microcontrollers, RF-ICs, High Power Amplifiers, Mixed Signal ICs, System-on-Chip (SoC), System-in-Package (SiP) and more. Established in 2003 as a joint venture between Hitachi, Ltd. (TSE:6501, NYSE:HIT) and Mitsubishi Electric Corporation (TSE:6503), Renesas Technology achieved consolidated revenue of 702.7 billion JPY in FY2008 (end of March 2009). Renesas Technology is based in Tokyo, Japan and has a global network of manufacturing, design and sales operations in 16 countries with 25,000 employees worldwide. For further information, please visit <http://www.renesas.com>

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